

JOM Call for papers

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Manuscript Deadline: *December 1, 2022*

Advanced Technology for Electronic Packaging and Interconnection Materials

Advanced progress in devices requires new materials and technologies to meet the electrical, thermal, mechanical, reliability and environmental demands. The special topic will address current research in new and existing materials for emerging interconnects and electronic packaging.

Original research papers should be 3,000-9,000 words with up to 12 figures maximum; review papers should be 6,000-11,000 words with up to 20 figures maximum.

Detailed author instructions are available at:

<http://www.tms.org/AuthorTools/>

Keywords for this topic: *Advanced Materials; Electronic Materials; Intermetallics; Joining; Thin Films and Interfaces*

Guest Editor(s): *Albert T. Wu:*
atwu@ncu.edu.tw

Committee Sponsor(s): *Electronic Packaging and Interconnection Materials*

If you are interested in submitting a paper, upload your manuscript at
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Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

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